

NCS20061, NCV20061, NCS20062, NCV20062, NCS20064, NCV20064

Rail-to-Rail Input and Output, 3 MHz Operational Amplifier

The NCS2006 series operational amplifiers provide rail-to-rail input and output operation, 3 MHz bandwidth, and are available in single, dual, and quad configurations. Rail-to-rail operation gives designers use of the entire supply voltage range while taking advantage of the 3 MHz bandwidth. The NCS2006 can operate on supply voltages from 1.8 to 5.5 V over a temperature range from -40 to 125°C. At a 1.8 V supply, this device has a slew rate of 1.2 V/μs while consuming only 125 μA of quiescent current per channel. Since this is a CMOS device, high input impedance and low bias currents make it ideal for interfacing to a wide variety of signal sensors. The NCS2006 devices are available in a variety of compact packages.

Features

- Rail-to-Rail Input and Output
- Wide Supply Range: 1.8 to 5.5 V
- Wide Bandwidth: 3 MHz
- High Slew Rate: 1.2 V/μs at $V_S = 1.8$ V
- Low Supply Current: 125 μA per Channel at $V_S = 1.8$ V
- Low Input Bias Current: 1 pA Typical
- Wide Temperature Range: -40 to 125°C
- Available in a Variety of Packages
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Unity Gain Buffer
- Battery Powered / Low Quiescent Current Applications
- Low Cost Current Sensing
- Automotive



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SC70-5
CASE 419AC



TSOP-5/SOT23-5
CASE 483



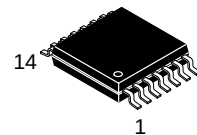
Micro8™/MSOP8
CASE 846A



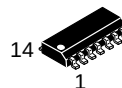
SOIC-8
CASE 751



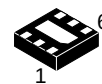
TSSOP-8
CASE 948S



TSSOP-14
CASE 948G



SOIC-14
CASE 751A



UDFN6
CASE 517AP

DEVICE MARKING INFORMATION

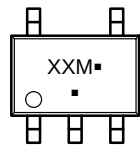
See general marking information in the device marking section on page 2 of this data sheet.

ORDERING INFORMATION

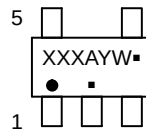
See detailed ordering and shipping information on page 3 of this data sheet.

MARKING DIAGRAMS

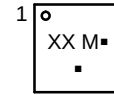
Single Channel Configuration NCS20061, NCV20061



SC70-5
CASE 419AC

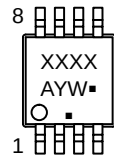


TSOP-5/SOT23-5
CASE 483

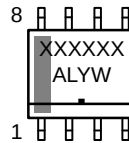


UDFN6
CASE 517AP

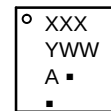
Dual Channel Configuration NCS20062, NCV20062



Micro8™/MSOP8
CASE 846A

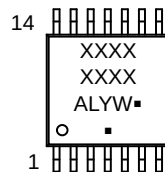


SOIC-8
CASE 751

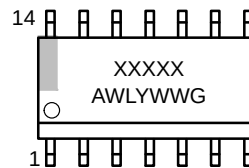


TSSOP-8
CASE 948S

Quad Channel Configuration NCS20064, NCV20064



TSSOP-14
CASE 948G



SOIC-14
CASE 751A

XXXXX = Specific Device Code
A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

NCS20061, NCV20061, NCS20062, NCV20062, NCS20064, NCV20064

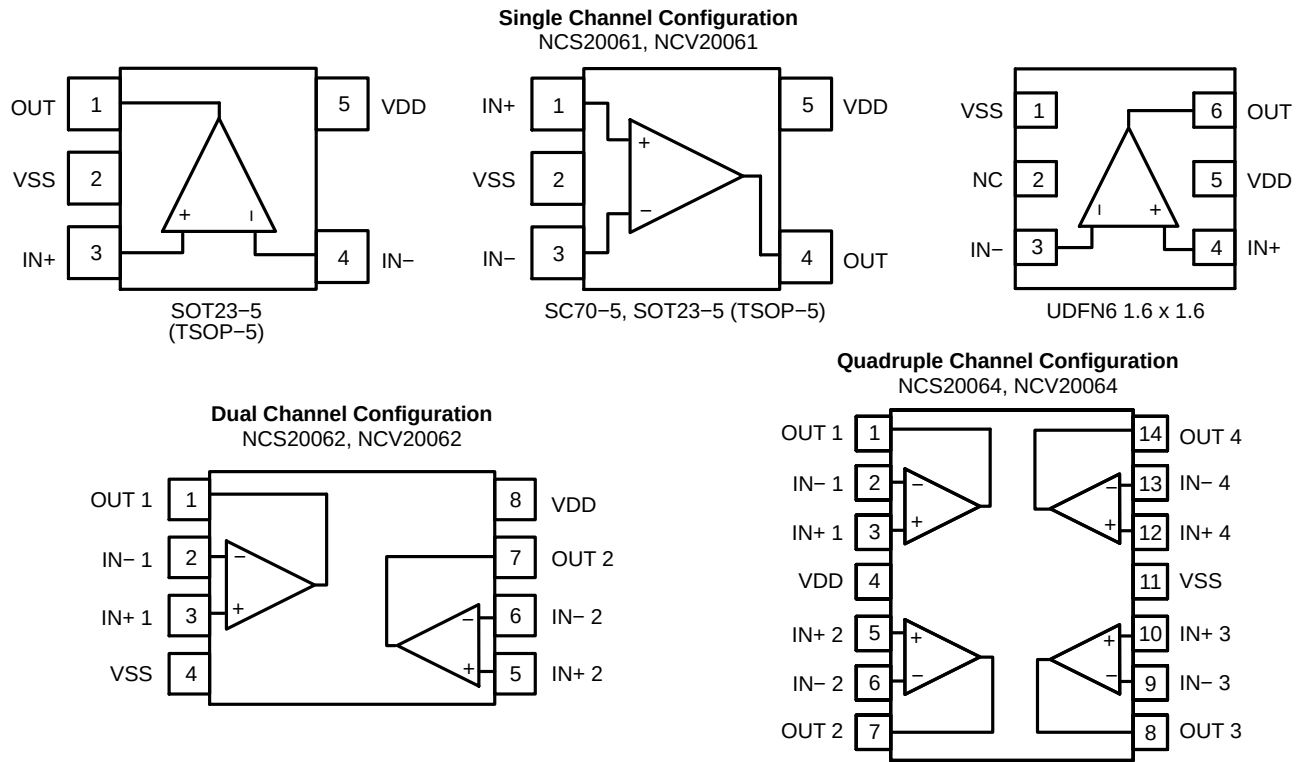


Figure 1. Pin Connections

ORDERING INFORMATION

Device	Configuration	Automotive	Marking	Package	Shipping [†]
NCS20061_	Single	No	TBD	SC70	Contact local sales office for more information
NCS20061_			TBD	SOT23-5/TSOP-5	
NCS20061_			TBD	SOT23-5/TSOP-5	
NCS20061_			TBD	UDFN6	
NCV20061_		Yes	TBD	SC70	
NCV20061_			TBD	SOT23-5/TSOP-5	
NCV20061_			TBD	SOT23-5/TSOP-5	
NCV20061_			TBD	UDFN6	
NCS20062DMR2G	Dual	No	2K62	Micro8/MSOP8	
NCS20062DR2G			NCS20062	SOIC-8	
NCS20062DTBR2G			K62	TSSOP-8	
NCV20062DMR2G		Yes	2K62	Micro8/MSOP8	
NCV20062DR2G			NCS20062	SOIC-8	
NCV20062DTBR2G			K62	TSSOP-8	
NCS20064_	Quad	No	TBD	SOIC-14	
NCS20064_			TBD	SOP-14	
NCS20064_			TBD	TSSOP-14	
NCV20064_		Yes	TBD	SOIC-14	
NCV20064_			TBD	SOP-14	
NCV20064_			TBD	TSSOP-14	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

*NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

ABSOLUTE MAXIMUM RATINGS (Note 1)

Rating	Symbol	Limit	Unit
Supply Voltage (V _{DD} – V _{SS}) (Note 2)	V _S	7	V
Input Voltage	V _I	V _{SS} – 0.5 to V _{DD} + 0.5	V
Differential Input Voltage	V _{ID}	±V _s	V
Maximum Input Current	I _I	±10	mA
Maximum Output Current	I _O	±100	mA
Continuous Total Power Dissipation (Note 2)	P _D	200	mW
Maximum Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	–65 to 150	°C
Mounting Temperature (Infrared or Convection – 20 sec)	T _{mount}	260	°C
ESD Capability (Note 3)	Human Body Model Machine Model Charge Device Model	ESD _{HBM} ESD _{MM} ESD _{CDM}	2000 100 2000
Latch-Up Current (Note 4)	I _{LU}	100	mA
Moisture Sensitivity Level (Note 5)	MSL	Level 1	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Refer to ELECTRICAL CHARACTERISTICS for Safe Operating Area.
2. Continuous short circuit operation to ground at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150°C. Output currents in excess of the maximum output current rating over the long term may adversely affect reliability. Shorting output to either VDD or VSS will adversely affect reliability.
3. This device series incorporates ESD protection and is tested by the following methods:
ESD Human Body Model tested per AEC-Q100-002 (JEDEC standard: JESD22-A114)
ESD Machine Model tested per AEC-Q100-003 (JEDEC standard: JESD22-A115)
4. Latch-up Current tested per JEDEC standard: JESD78
5. Moisture Sensitivity Level tested per IPC/JEDEC standard: J-STD-020A

THERMAL INFORMATION

Parameter	Symbol	Channels	Package	Single Layer Board (Note 6)	Multi-Layer Board (Note 7)	Unit
Junction to Ambient Thermal Resistance	θ_{JA}	Single	SC-70			°C/W
			SOT23-5/TSOP-5			
			UDFN6			
		Dual	Micro8/MSOP8	236	167	
			SOIC-8	190	131	
			TSSOP-8	253	194	
		Quad	SOIC-14			
			SOP-14			
			TSSOP-14			

6. Value based on 1S standard PCB according to JEDEC51-3 with 1.0 oz copper and a 300 mm² copper area

7. Value based on 1S2P standard PCB according to JEDEC51-7 with 1.0 oz copper and a 100 mm² copper area

OPERATING RANGES

Parameter	Symbol	Min	Max	Unit
Operating Supply Voltage	V_S	1.8	5.5	V
Differential Input Voltage	V_{ID}		V_S	V
Input Common Mode Range	V_{ICM}	$V_{SS} - 0.2$	$V_{DD} + 0.2$	V
Ambient Temperature	T_A	-40	125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

ELECTRICAL CHARACTERISTICS AT $V_S = 1.8\text{ V}$

$T_A = 25^\circ\text{C}$; $R_L \geq 10\text{ k}\Omega$; $V_{CM} = V_{OUT} = \text{mid-supply}$ unless otherwise noted.

Boldface limits apply over the specified temperature range, $T_A = -40^\circ\text{C}$ to 125°C . (Note 8)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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INPUT CHARACTERISTICS

Input Offset Voltage	V_{OS}			0.5	3.5	mV
					4	mV
Offset Voltage Drift	$\Delta V_{OS}/\Delta T$			1		$\mu\text{V}/^\circ\text{C}$
Input Bias Current (Note 8)	I_{IB}			1		pA
					1500	pA
Input Offset Current (Note 8)	I_{OS}			1		pA
					1100	pA
Channel Separation	XTLK	DC		125		dB
Differential Input Resistance	R_{ID}			10		$\text{G}\Omega$
Common Mode Input Resistance	R_{IN}			10		$\text{G}\Omega$
Differential Input Capacitance	C_{ID}			1		pF
Common Mode Input Capacitance	C_{CM}			5		pF
Common Mode Rejection Ratio	CMRR	$V_{CM} = V_{SS} - 0.2$ to $V_{DD} + 0.2$	48	73		dB
		$V_{CM} = V_{SS} + 0.2$ to $V_{DD} - 0.2$	45			

OUTPUT CHARACTERISTICS

Open Loop Voltage Gain	A_{VOL}		86	120		dB
			80			
Short Circuit Current	I_{SC}	Output to positive rail, sinking current		19		mA
		Output to negative rail, sourcing current		15		
Output Voltage High	V_{OH}	Voltage output swing from positive rail		3	19	mV
					20	
Output Voltage Low	V_{OL}	Voltage output swing from negative rail		3	19	mV
					20	

AC CHARACTERISTICS

Unity Gain Bandwidth	UGBW			3		MHz
Slew Rate at Unity Gain	SR	$V_{ID} = 1.2\text{ Vpp}$, Gain = 1		1.2		$\text{V}/\mu\text{s}$
Phase Margin	ψ_m			60		$^\circ$
Gain Margin	A_m			10		dB
Settling Time	t_S	$V_{IN} = 1.2\text{ Vpp}$, Gain = 1	Settling time to 0.1%	2.3		μs
			Settling time to 0.01%	6		
Open Loop Output Impedance	Z_{OL}	$f = 100\text{ Hz}$		0.05		Ω

NOISE CHARACTERISTICS

Total Harmonic Distortion plus Noise	THD+N	$V_{IN} = 1.2\text{ Vpp}$, $f = 1\text{ kHz}$, $A_v = 1$		0.005		%
Input Referred Voltage Noise	e_n	$f = 1\text{ kHz}$		20		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ kHz}$		15		
Input Referred Current Noise	i_n	$f = 1\text{ kHz}$		300		$\text{fA}/\sqrt{\text{Hz}}$

SUPPLY CHARACTERISTICS

Power Supply Rejection Ratio	PSRR	No Load	67	90		dB
			64			
Power Supply Quiescent Current	I_{DD}	Per channel, no load		125	170	μA

8. Performance guaranteed over the indicated operating temperature range by design and/or characterization.

ELECTRICAL CHARACTERISTICS AT $V_S = 3.3\text{ V}$

$T_A = 25^\circ\text{C}$; $R_L \geq 10\text{ k}\Omega$; $V_{CM} = V_{OUT} = \text{mid-supply}$ unless otherwise noted.

Boldface limits apply over the specified temperature range, $T_A = -40^\circ\text{C}$ to 125°C . (Note 9)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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INPUT CHARACTERISTICS

Input Offset Voltage	V_{OS}			0.5	3.5	mV
					4	mV
Offset Voltage Drift	$\Delta V_{OS}/\Delta T$			1		$\mu\text{V}/^\circ\text{C}$
Input Bias Current (Note 9)	I_{IB}			1		pA
					1500	pA
Input Offset Current (Note 9)	I_{OS}			1		pA
					1100	pA
Channel Separation	XTLK	DC		125		dB
Differential Input Resistance	R_{ID}			10		$\text{G}\Omega$
Common Mode Input Resistance	R_{IN}			10		$\text{G}\Omega$
Differential Input Capacitance	C_{ID}			1		pF
Common Mode Input Capacitance	C_{CM}			5		pF
Common Mode Rejection Ratio	CMRR	$V_{CM} = V_{SS} - 0.2$ to $V_{DD} + 0.2$	53	76		dB
		$V_{CM} = V_{SS} + 0.2$ to $V_{DD} - 0.2$	48			

OUTPUT CHARACTERISTICS

Open Loop Voltage Gain	A_{VOL}		90	120		dB
			86			
Short Circuit Current	I_{SC}	Output to positive rail, sinking current		19		mA
		Output to negative rail, sourcing current		15		
Output Voltage High	V_{OH}	Voltage output swing from positive rail		3	24	mV
					25	
Output Voltage Low	V_{OL}	Voltage output swing from negative rail		3	24	mV
					25	

AC CHARACTERISTICS

Unity Gain Bandwidth	UGBW			3		MHz
Slew Rate at Unity Gain	SR	$V_{IN} = 2.5\text{ Vpp}$, Gain = 1		1.2		$\text{V}/\mu\text{s}$
Phase Margin	ψ_m			60		$^\circ$
Gain Margin	A_m			10		dB
Settling Time	t_S	$V_{IN} = 2.5\text{ Vpp}$, Gain = 1	Settling time to 0.1%	2.3		μs
			Settling time to 0.01%	3.1		
Open Loop Output Impedance	Z_{OL}	$f = 100\text{ Hz}$		0.05		Ω

NOISE CHARACTERISTICS

Total Harmonic Distortion plus Noise	THD+N	$V_{IN} = 2.5\text{ Vpp}$, $f = 1\text{ kHz}$, $A_v = 1$		0.005		%
Input Referred Voltage Noise	e_n	$f = 1\text{ kHz}$		20		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ kHz}$		15		
Input Referred Current Noise	i_n	$f = 1\text{ kHz}$		300		$\text{fA}/\sqrt{\text{Hz}}$

SUPPLY CHARACTERISTICS

Power Supply Rejection Ratio	PSRR	No Load	67	90		dB
			64			
Power Supply Quiescent Current	I_{DD}	Per channel, no load		135	180	μA

9. Performance guaranteed over the indicated operating temperature range by design and/or characterization.

ELECTRICAL CHARACTERISTICS AT $V_S = 5.5\text{ V}$

$T_A = 25^\circ\text{C}$; $R_L \geq 10\text{ k}\Omega$; $V_{CM} = V_{OUT} = \text{mid-supply}$ unless otherwise noted.

Boldface limits apply over the specified temperature range, $T_A = -40^\circ\text{C}$ to 125°C . (Note 10)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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INPUT CHARACTERISTICS

Input Offset Voltage	V_{OS}			0.5	3.5	mV
					4	mV
Offset Voltage Drift	$\Delta V_{OS}/\Delta T$			1		$\mu\text{V}/^\circ\text{C}$
Input Bias Current (Note 10)	I_{IB}			1		pA
					1500	pA
Input Offset Current (Note 10)	I_{OS}			1		pA
					1100	pA
Channel Separation	XTLK	DC		125		dB
Differential Input Resistance	R_{ID}			10		$\text{G}\Omega$
Common Mode Input Resistance	R_{IN}			10		$\text{G}\Omega$
Differential Input Capacitance	C_{ID}			1		pF
Common Mode Input Capacitance	C_{CM}			5		pF
Common Mode Rejection Ratio	CMRR	$V_{CM} = V_{SS} - 0.2 \text{ to } V_{DD} + 0.2$	55	79		dB
		$V_{CM} = V_{SS} + 0.2 \text{ to } V_{DD} - 0.2$	51			

OUTPUT CHARACTERISTICS

Open Loop Voltage Gain	A_{VOL}		90	120		dB
			86			
Short Circuit Current	I_{SC}	Output to positive rail, sinking current		19		mA
		Output to negative rail, sourcing current		15		
Output Voltage High	V_{OH}	Voltage output swing from positive rail		3	24	mV
					25	
Output Voltage Low	V_{OL}	Voltage output swing from negative rail		3	24	mV
					25	

AC CHARACTERISTICS

Unity Gain Bandwidth	UGBW			3		MHz
Slew Rate at Unity Gain	SR	$V_{ID} = 5\text{ Vpp}$, Gain = 1		1.2		$\text{V}/\mu\text{s}$
Phase Margin	ψ_m			60		$^\circ$
Gain Margin	A_m			10		dB
Settling Time	t_S	$V_{IN} = 5\text{ Vpp}$, Gain = 1	Settling time to 0.1%	2.3		μs
			Settling time to 0.01%	3.1		
Open Loop Output Impedance	Z_{OL}	$f = 100\text{ Hz}$		0.05		Ω

NOISE CHARACTERISTICS

Total Harmonic Distortion plus Noise	THD+N	$V_{IN} = 5\text{ Vpp}$, $f = 1\text{ kHz}$, $A_v = 1$		0.005		%
Input Referred Voltage Noise	e_n	$f = 1\text{ kHz}$		20		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ kHz}$		15		
Input Referred Current Noise	i_n	$f = 1\text{ kHz}$		300		$\text{fA}/\sqrt{\text{Hz}}$

SUPPLY CHARACTERISTICS

Power Supply Rejection Ratio	PSRR	No Load	67	90		dB
			64			
Power Supply Quiescent Current	I_{DD}	Per channel, no load		140	200	μA

10. Performance guaranteed over the indicated operating temperature range by design and/or characterization.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL PERFORMANCE CHARACTERISTICS

$T_A = 25^\circ\text{C}$, $R_L \geq 10\text{ k}\Omega$, $V_{CM} = V_{OUT} = \text{mid-supply}$ unless otherwise specified

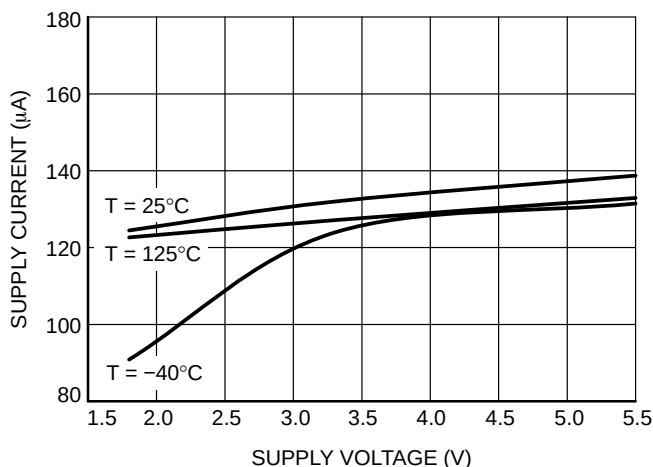


Figure 2. Quiescent Current per Channel vs. Supply Voltage

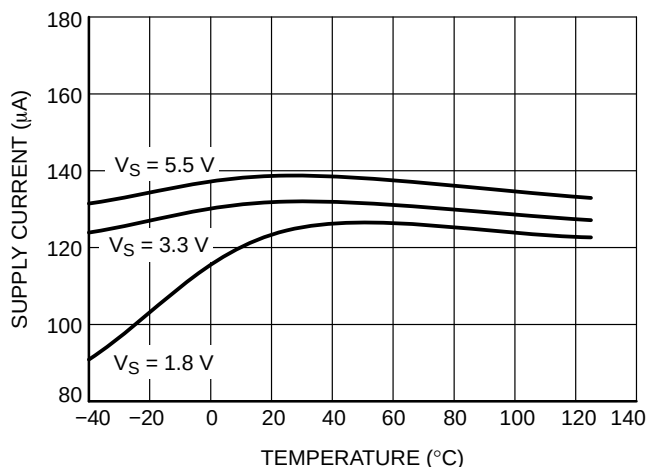


Figure 3. Quiescent Current vs. Temperature

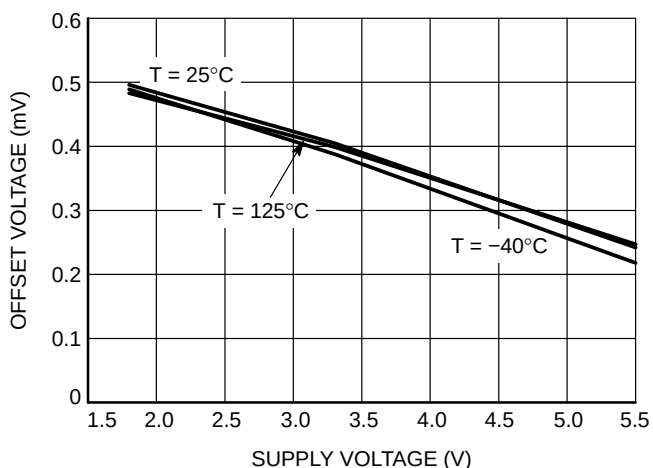


Figure 4. Offset Voltage vs. Supply Voltage

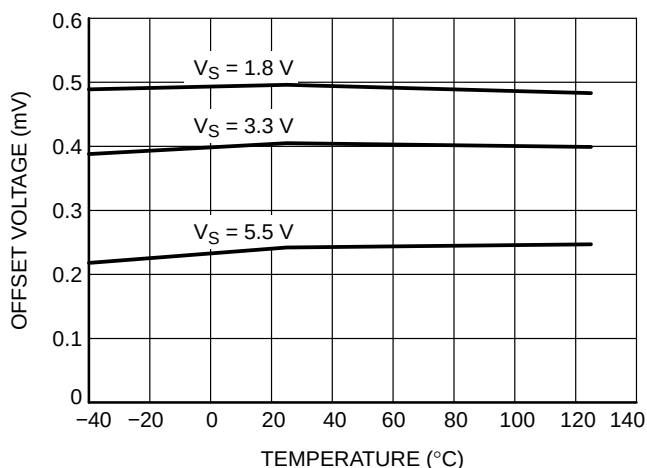


Figure 5. Offset Voltage vs. Temperature

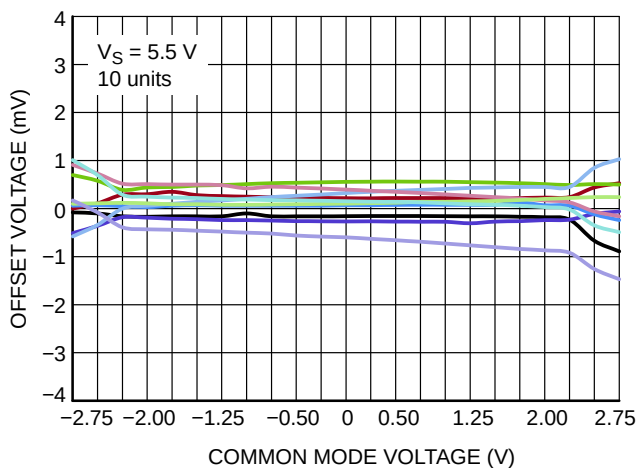


Figure 6. Offset Voltage vs. Common Mode Voltage

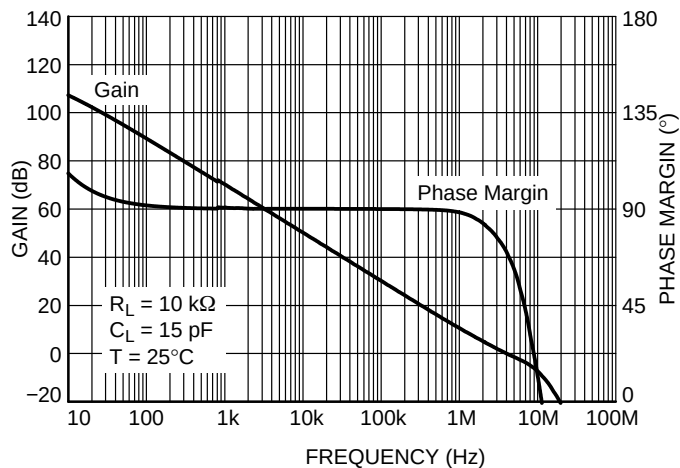


Figure 7. Open-loop Gain and Phase Margin vs. Frequency

TYPICAL PERFORMANCE CHARACTERISTICS

$T_A = 25^\circ\text{C}$, $R_L \geq 10\text{ k}\Omega$, $V_{CM} = V_{OUT} = \text{mid-supply}$ unless otherwise specified

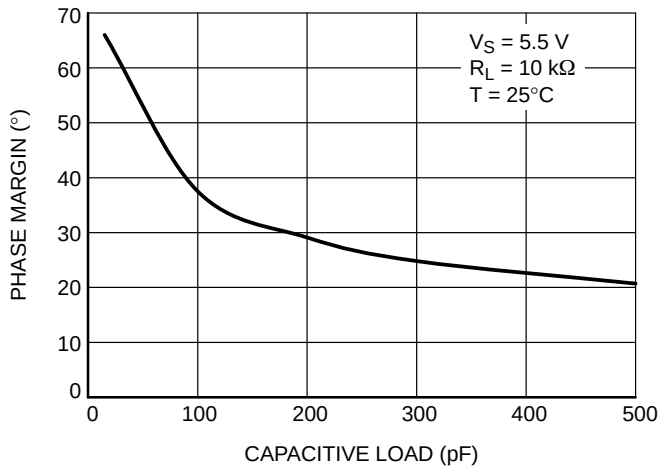


Figure 8. Phase Margin vs. Capacitive Load

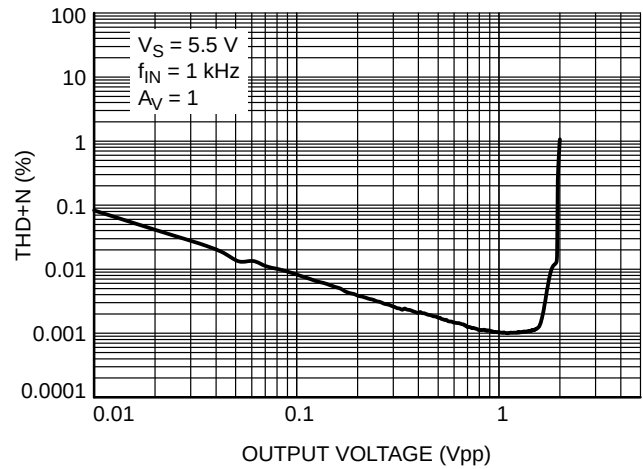


Figure 9. THD + N vs. Output Voltage

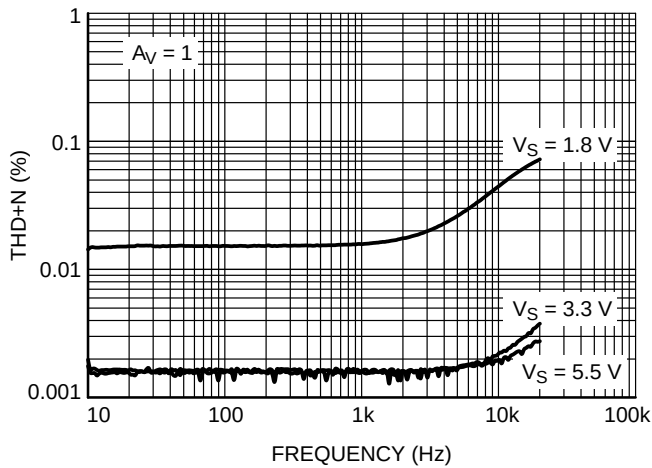


Figure 10. THD + N vs. Frequency

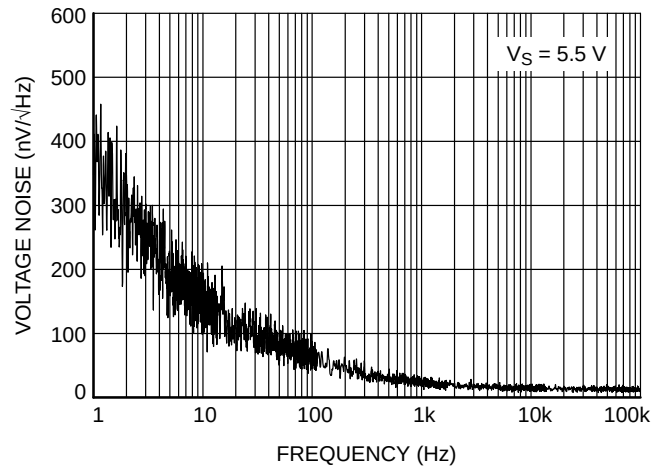


Figure 11. Input Voltage Noise vs. Frequency

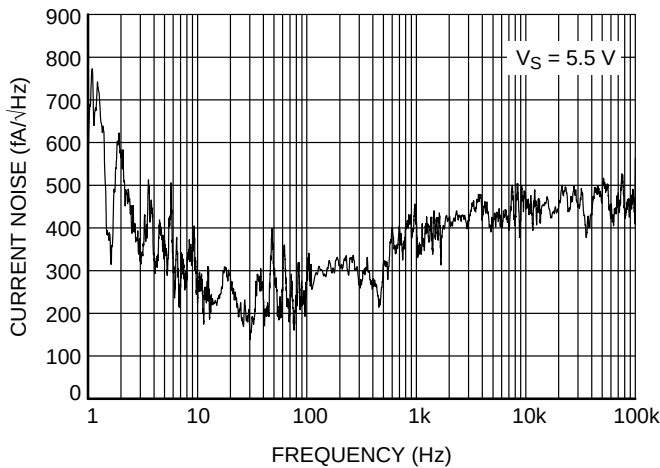


Figure 12. Input Current Noise vs. Frequency

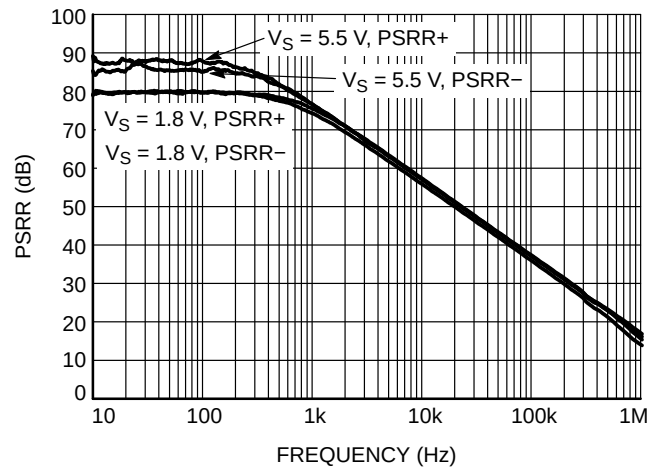


Figure 13. PSRR vs. Frequency

TYPICAL PERFORMANCE CHARACTERISTICS

$T_A = 25^\circ\text{C}$, $R_L \geq 10\text{ k}\Omega$, $V_{CM} = V_{OUT} = \text{mid-supply unless otherwise specified}$

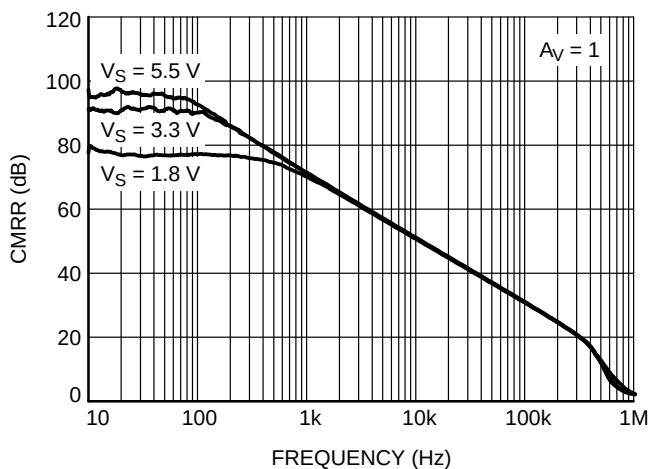


Figure 14. CMRR vs. Frequency

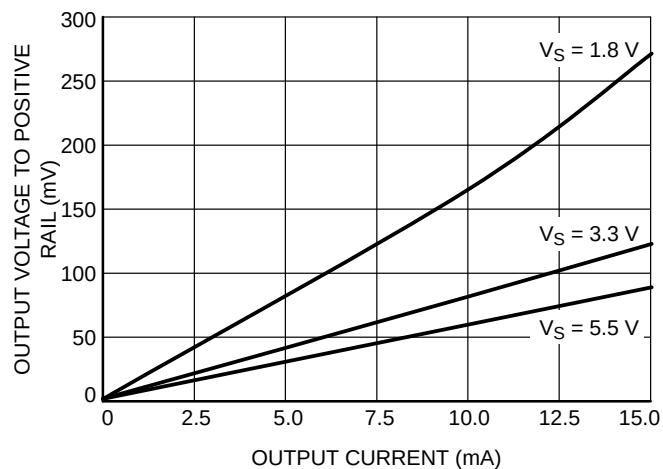


Figure 15. Output Voltage High to Rail

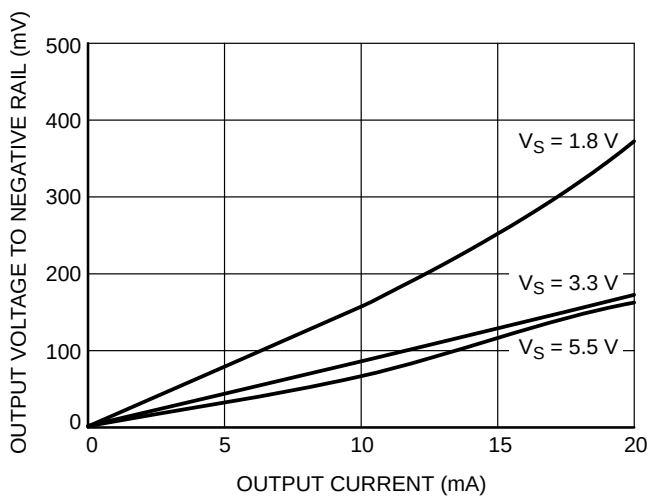


Figure 16. Output Voltage Low to Rail

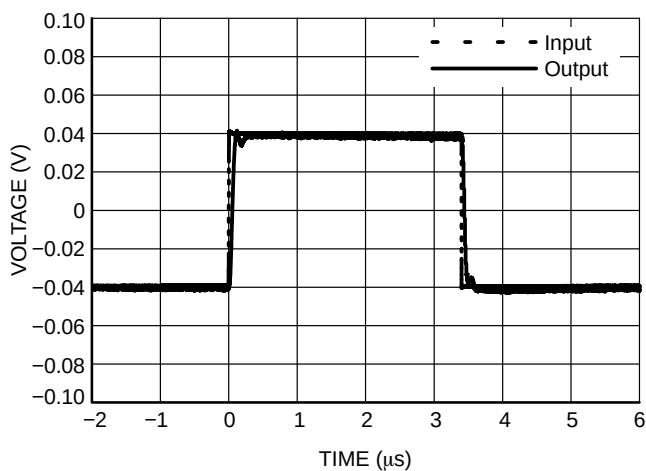


Figure 17. Non-Inverting Small Signal Transient Response

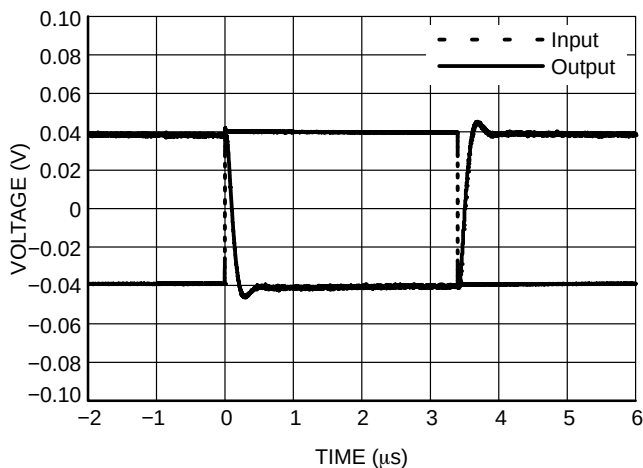


Figure 18. Inverting Small Signal Transient Response

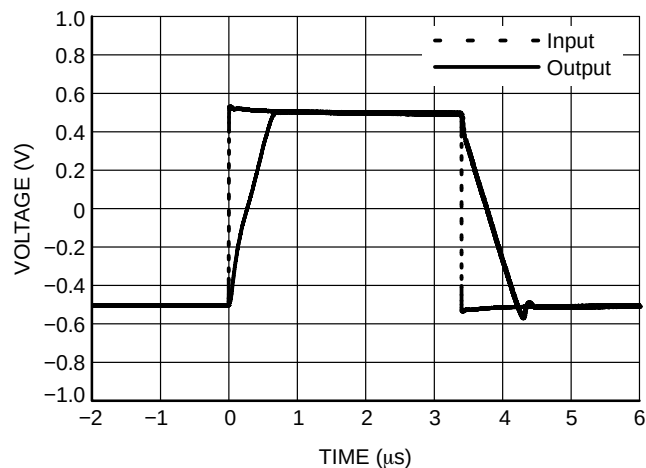


Figure 19. Non-Inverting Large Signal Transient Response

TYPICAL PERFORMANCE CHARACTERISTICS

$T_A = 25^\circ\text{C}$, $R_L \geq 10\text{ k}\Omega$, $V_{CM} = V_{OUT} = \text{mid-supply}$ unless otherwise specified

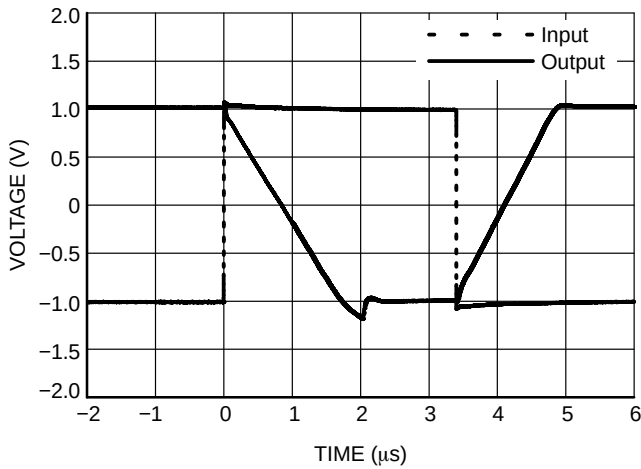


Figure 20. Inverting Large Signal Transient Response

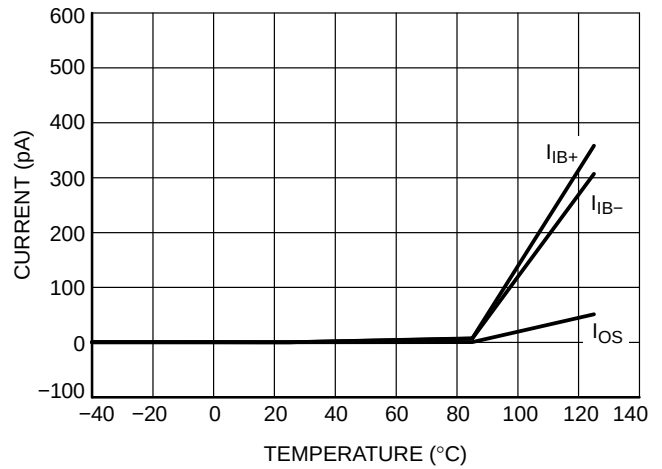


Figure 21. Input Bias and Offset Current vs. Temperature

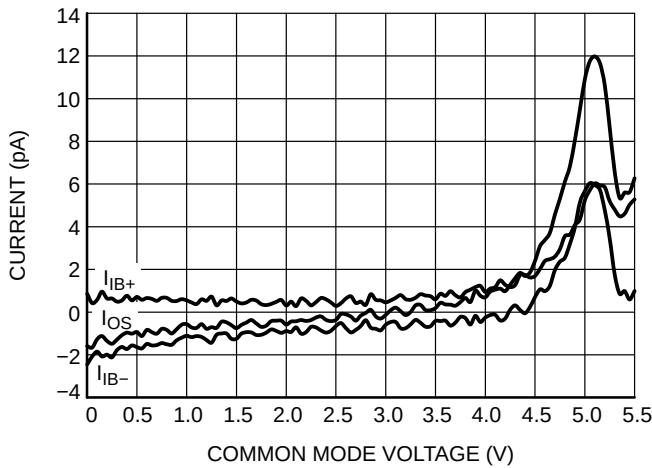


Figure 22. Input Bias Current vs. Common Mode Voltage

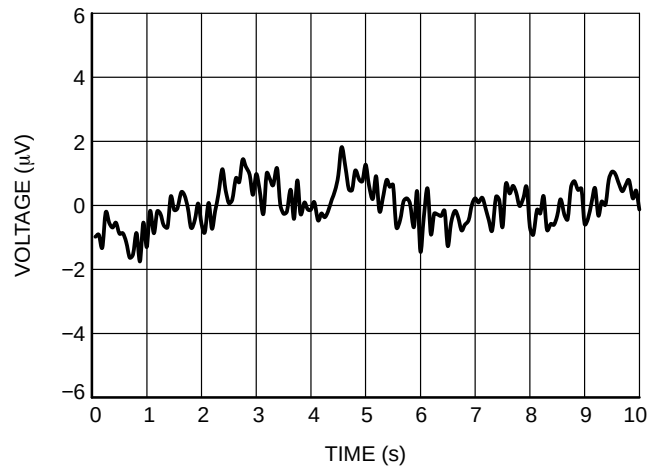


Figure 23. 0.1 Hz to 10 Hz Noise

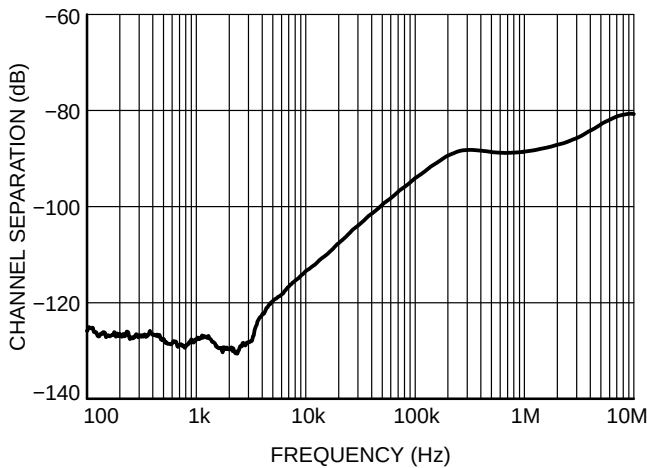


Figure 24. Channel Separation vs. Frequency

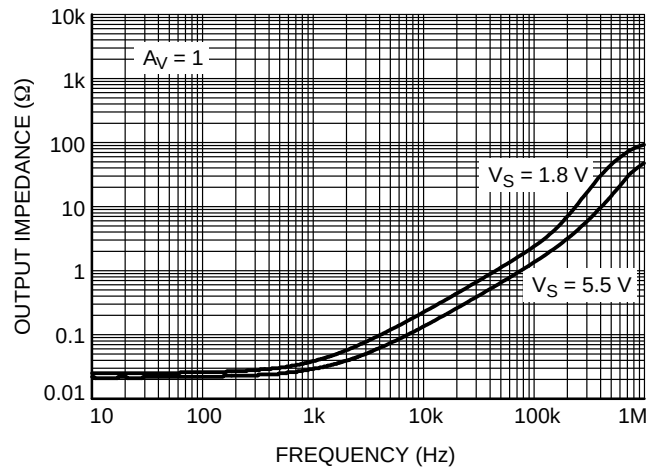


Figure 25. Output Impedance vs. Frequency

TYPICAL PERFORMANCE CHARACTERISTICS

$T_A = 25^\circ\text{C}$, $R_L \geq 10\text{ k}\Omega$, $V_{CM} = V_{OUT} = \text{mid-supply}$ unless otherwise specified

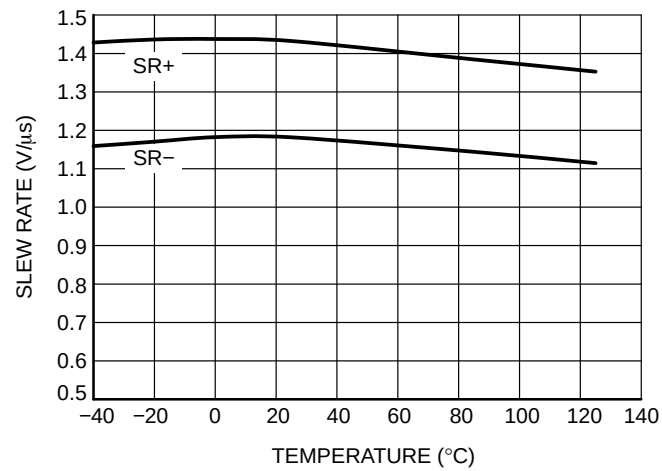
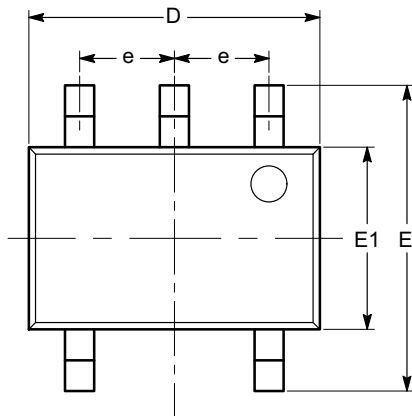


Figure 26. Slew Rate vs. Temperature

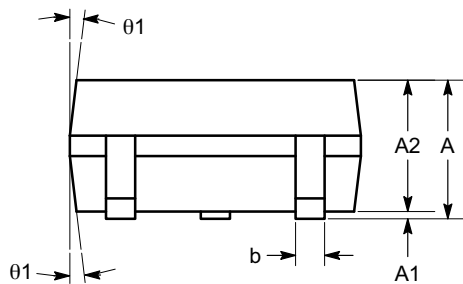
PACKAGE DIMENSIONS

SC-88A (SC-70 5 Lead), 1.25x2
CASE 419AC-01
ISSUE A

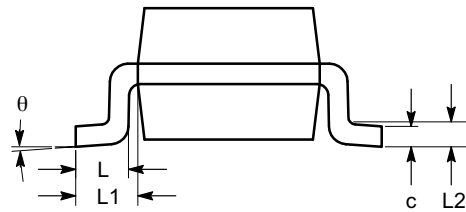


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	0.80		1.10
A1	0.00		0.10
A2	0.80		1.00
b	0.15		0.30
c	0.10		0.18
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
e	0.65 BSC		
L	0.26	0.36	0.46
L1	0.42 REF		
L2	0.15 BSC		
θ	0°		8°
θ_1	4°		10°



SIDE VIEW



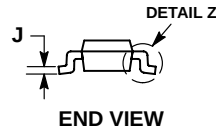
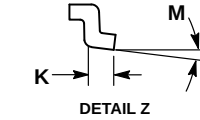
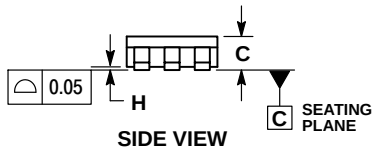
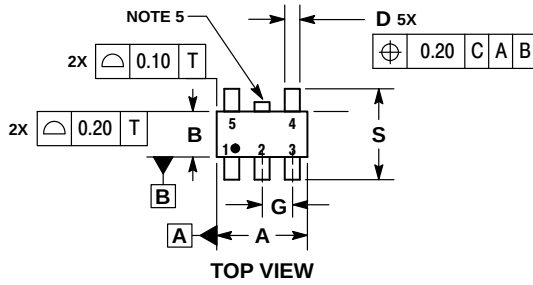
END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-203.

PACKAGE DIMENSIONS

TSOP-5
CASE 483-02
ISSUE K

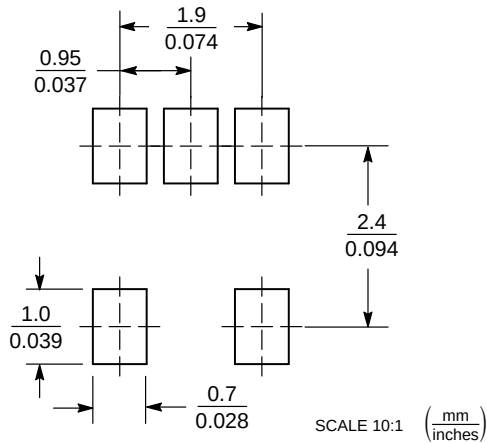


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

DIM	MILLIMETERS	
	MIN	MAX
A	3.00	BSC
B	1.50	BSC
C	0.90	1.10
D	0.25	0.50
G	0.95	BSC
H	0.01	0.10
J	0.10	0.26
K	0.20	0.60
M	0°	10°
S	2.50	3.00

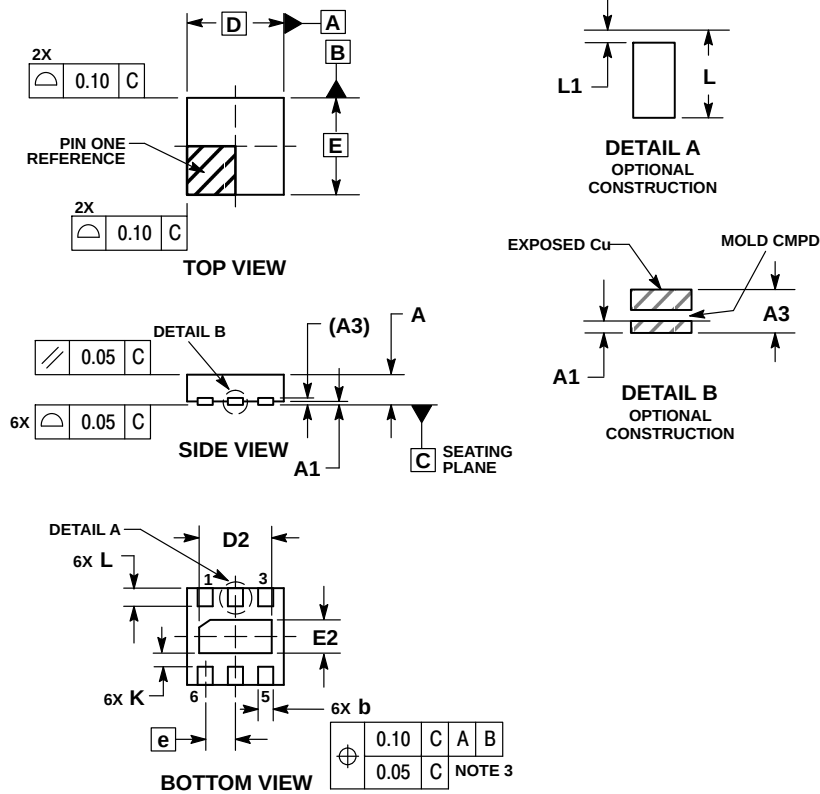
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN6 1.6x1.6, 0.5P
CASE 517AP-01
ISSUE O

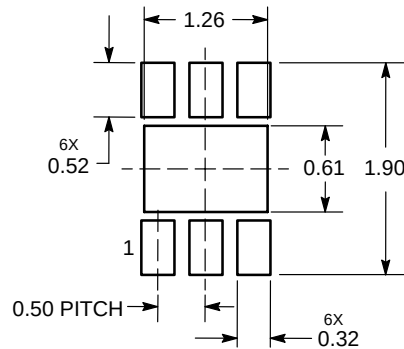


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.20	0.30
D	1.60	BSC
E	1.60	BSC
e	0.50	BSC
D2	1.10	1.30
E2	0.45	0.65
K	0.20	---
L	0.20	0.40
L1	0.00	0.15

SOLDERMASK DEFINED
MOUNTING FOOTPRINT*

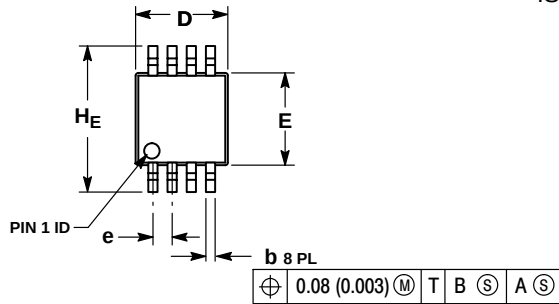


DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

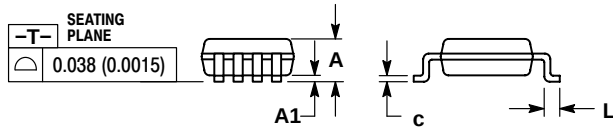
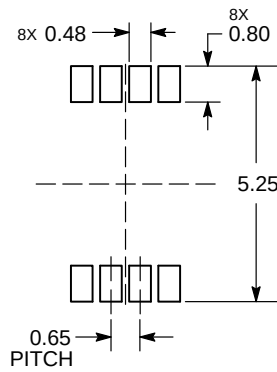
Micro8™
CASE 846A-02
ISSUE J



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. 846A-01 OBSOLETE, NEW STANDARD 846A-02.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	—	—	1.10	—	—	0.043
A1	0.05	0.08	0.15	0.002	0.003	0.006
b	0.25	0.33	0.40	0.010	0.013	0.016
c	0.13	0.18	0.23	0.005	0.007	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
E	2.90	3.00	3.10	0.114	0.118	0.122
e	0.65 BSC			0.026 BSC		
L	0.40	0.55	0.70	0.016	0.021	0.028
HE	4.75	4.90	5.05	0.187	0.193	0.199

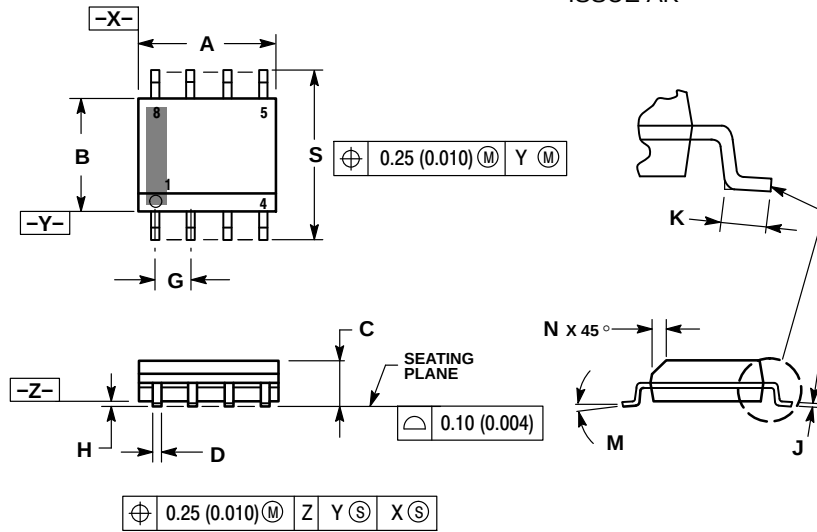
RECOMMENDED
SOLDERING FOOTPRINT*

DIMENSION: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOIC-8 NB
CASE 751-07
ISSUE AK



NOTES:

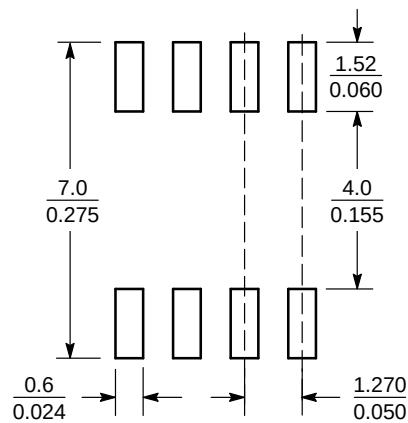
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

STYLE 11:

- PIN 1: SOURCE 1
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN 2
6. DRAIN 2
7. DRAIN 1
8. DRAIN 1

SOLDERING FOOTPRINT*

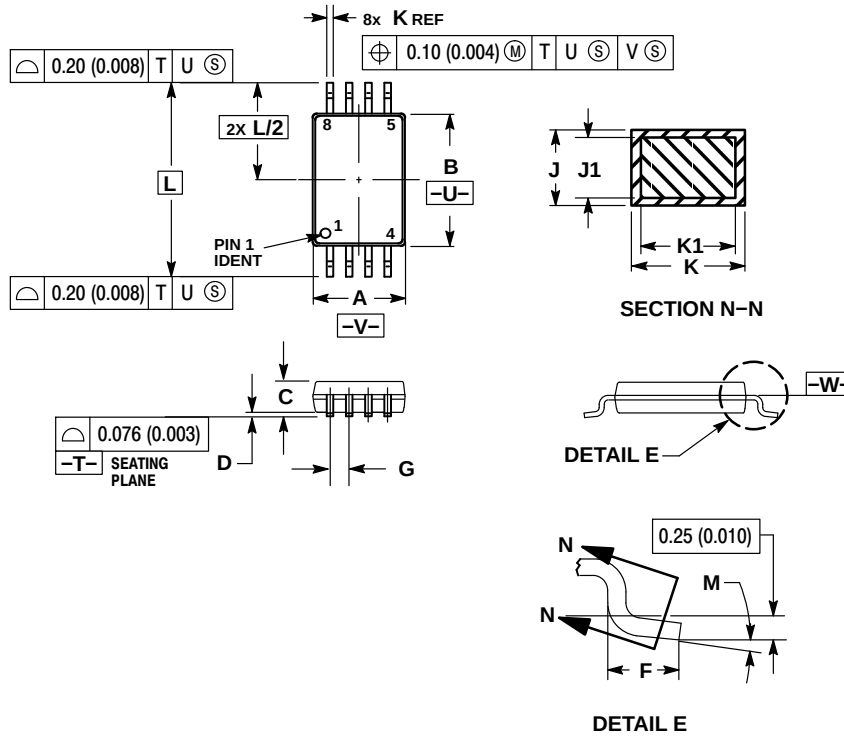


SCALE 6:1 (mm/inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

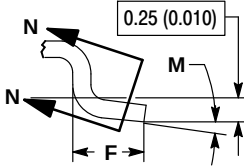
TSSOP-8
CASE 948S-01
ISSUE C



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

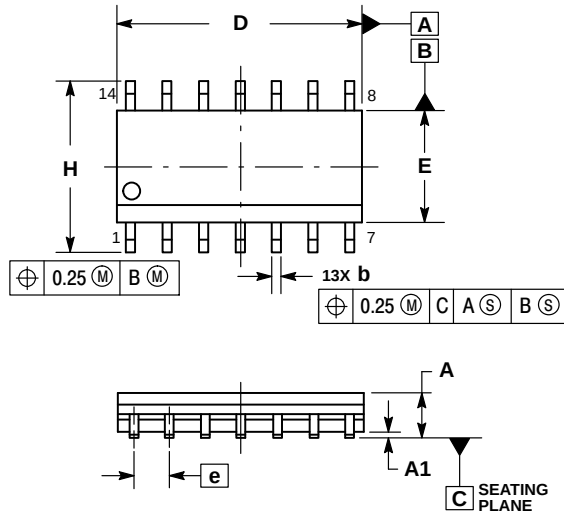
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	4.30	4.50	0.169	0.177
C	---	1.10	---	0.043
D	0.05	0.15	0.002	0.006
F	0.50	0.70	0.020	0.028
G	0.65 BSC		0.026 BSC	
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°



DETAIL E

PACKAGE DIMENSIONS

SOIC-14 NB
CASE 751A-03
ISSUE K

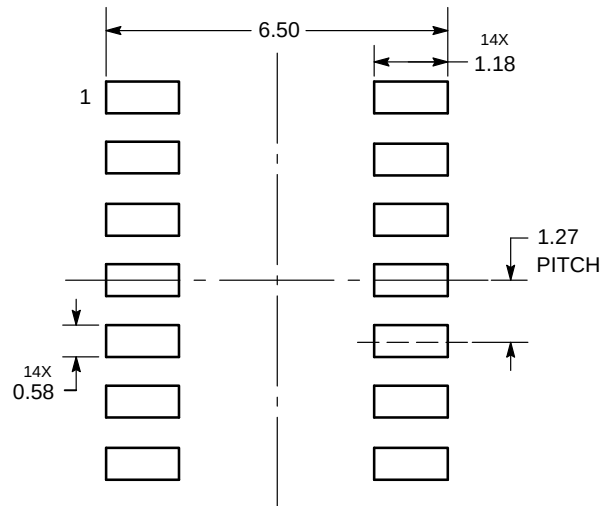


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

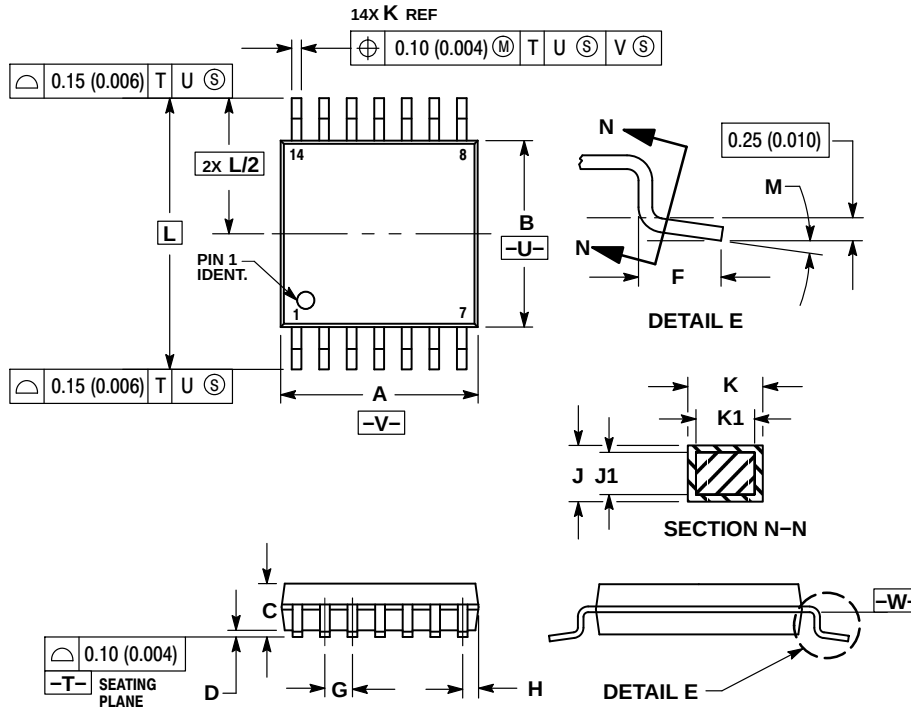
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

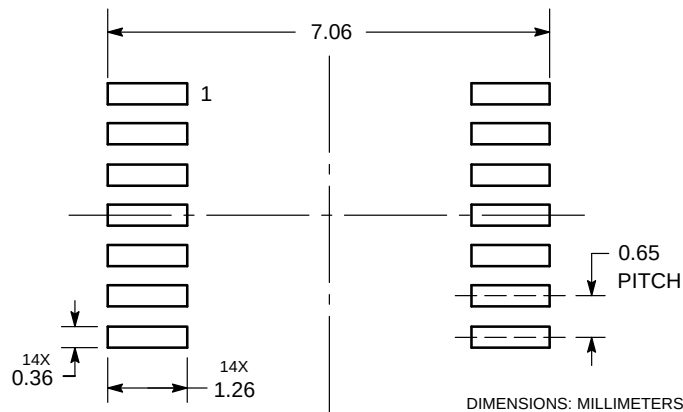
TSSOP-14
CASE 948G-01
ISSUE B

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT



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